Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
		S49 and S52 and (electron near tunneling) same S54 not S56 and (thermotunneling thermo adj2 tunneling thermionic therm adj ionic	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 19:33
		S49 and S52 and (electron near10 (tunneling tunnel) same S54 not S56 and temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 18:00
		S30 and collector same emitter same S32 same S35 same S38	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:51
		S30 and collector same emitter same S32 same S35 same S38	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:51
		S30 and collector same emitter same S32 same S32 same S35 same S32 same S38	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:51
		S30 and collector same emitter same S32 same S35 same S32 same S38	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:51
		"257"/\$.ccls. and @ad<"20040607" and thermal same (dissipate dissipation dissipated) same top same bottom same (component IC circuit) and (circuit near adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/14 16:27
		S6 and same (top and bottom)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/06 21:45
L1	2	("6806629").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/10 13:27

	22	(844407008 845145038	LIC DCDLID:	OR	ON	2006/10/10 14:03
L2	33	("4448799" "4511593" "4556471" "4620913" "4622452" "4640744" "5028546" "5294322" "5458754" "5562781" "5614353" "5675972" "5679895" "5712488" "5713775" "5722242" "5777427" "5874039" "5959400" "5981071" "5984752" "5994638" "6039471" "6055815" "6064137" "6066399" "6103298" "6132278" "6139964" "6204595" "6214651" "6229083" "6278231").PN.	US-PGPUB; USPAT; USOCR	OK .	ON	2000/10/10 14:03
L3	19	("5356484" "5569973" "5598052").PN. OR ("5675972"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/10 13:32
L4	2	("6779347").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/10 14:04
L5	1	l4 and aluminum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/10 14:04
L6	5	"6876123"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/10 14:04
L7	2	("6876123").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/10 14:05
L8	0	I7 and aliminum near oxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/10 14:05

L9	. 1	I7 and aluminum near oxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/10 14:24
L10	0	"20030168957".pn. and electron near3 tunneling	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/10 14:24
L11	0	"20030168957".pn. and electron near10 tunneling	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/10 14:24
L12	40825	"20030168957".pn. tunneling	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/10 14:24
L13	0	"20030168957".pn. and tunneling	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/10 14:25
L14	2	"20030168957".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/10 14:25
L15	1	"20030168957".pn. and electron near tunnel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/10/10 14:26
L16	1	"20030168957".pn. and electron near tunnel and tunnel\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/10 14:26

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L17	17	(US-20040050415-\$ or	US-PGPUB;	OR	ON	2006/10/10 16:10
		US-20040207037-\$ or US-20030165617-\$ or US-20050275330-\$).did. or (US-5572042-\$ or US-5291274-\$ or US-7105852-\$ or US-4373142-\$ or US-6396191-\$ or US-6779347-\$ or	USPAT			
		US-5675972-\$ or US-6064137-\$ or US-6644036-\$ or US-6783418-\$ or US-7003962-\$ or US-5713775-\$ or US-6278231-\$).did.			•	
L18	2	("6806629").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/10 16:10
S1		"20050082661"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/10 15:15
·S2	9	"6464513"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/10 15:16

S3	102	("3516155" "3573617"	US-PGPUB;	OR	ON	2006/05/10 15:24
		"3670409" "4210383" "4713611"	USPAT;			
			USOCR	;		
		"4774632" "4893172" "4902606"				
		"4975079" "5006792" "5015191"				
		"5034802" "5054193"			•	
	1	"5073117" "5086337" "5097101"				
		"5139427" "5144747"				
		"5149662" "5152695" "5153814"				
		"5173055" "5175410"				
	•	"5175491" "5198963" "5208529"				
						,
		"5289117" "5321277" "5329423"				10
		"5367253" "5376010"				
i	["5390078" "5396032" "5400220"				
		"5420506" "5476211"				
	1	"5477086" "5477161" "5502397"				
}		"5517515" "5556293"				
		"5570033" "5578870" "5602422"				
		"5611705" "5628635"				
		"5629837" "5632631" "5637008"				
		"5646447" "5646542"				
		"5648893" "5655926" "5656945"				
		"5669774" "5686843"				,
		"5691041" "5692911" "5702255"				
		"5727954" "5730606"				
		"5746608" "5751554" "5786704"		1		
		"5789271" "5800205"				
		"5802699" "5810609" "5812378"				
		"5823800" "5829988"				
		"5857858" "5887344" "5888837"				
		"5905383" "5923181"				
		"5934914" "5947751" "5955888"				
		"5959840" "5973340"				
		"5973394" "5978223" "5982185"				
		"5983492" "5984694"			,	
		"6002590" "6007349" "6020597"				
		"6036503" "6037667"				
		"6042387" "6043563" "6062874"				
		"RE36217").PN.				
S4	6	"6464513"	US-PGPUB;	OR	ON	2006/05/10 15:25
	İ		USPAT;			
			USOCR		1	
CE	2	("6464513") DN	US-PGPUB;	OR	OFF	2006/05/10 15:26
S5	2	("6464513").PN.	USPAT;	OIX		2000,00,10 13.20
			USOCR;			1
			EPO; JPO;			
			DERWENT;			
		·	IBM_TDB			
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S6 .	267559	pcb or (printed near circuit near board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/10 15:26
S7	15447	S6 same (top and bottom)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/10 15:27
S8	14602	multi-chip\$1 or (multi-stack\$2 near chip\$1) or (multiple near (chip\$1 or device\$1 or dice\$1) near stack\$2) or (multi-stack\$2 near package\$2)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/10 15:28
S9	469	S7 and S8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/10 16:00
S10	2	"20030064547"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/10 16:02
S11	2	"6815251"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/10 16:02
S12	54	S9 and micron.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR -	ON	2006/05/10 16:44
S13	132	"5811879"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/10 16:45

S14	0	"58115723907879"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/10 16:45
S15	42	"5723907"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/14 16:02
S16	2	("5723907").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	OFF	2006/05/14 16:19
S17	5051	"257"/\$.ccls. and @ad<"20040607" and thermal and (dissipate dissipation dissipated) and top same bottom	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/14 16:22
S18	2010	"257"/\$.ccls. and @ad<"20040607" and thermal and (dissipate dissipation dissipated) and top same bottom and (circuit near board) and component	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/14 16:24
S19	2010	"257"/\$.ccls. and @ad<"20040607" and thermal and (dissipate dissipation dissipated) and top same bottom and (circuit near board) and component	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/14 16:25
S20	172	"257"/\$.ccls. and @ad<"20040607" and thermal same (dissipate dissipation dissipated) same top same bottom and (circuit near board) and component	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/14 16:25
S21 _	57	"257"/\$.ccls. and @ad<"20040607" and thermal same (dissipate dissipation dissipated) same top same bottom same (circuit near board) and component	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/14 16:26

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S22	133	"257"/\$.ccls. and @ad<"20040607" and thermal same (dissipate dissipation dissipated) same top same bottom same (component IC circuit) and (circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/14 16:28
S23	65	"257"/\$.ccls. and @ad<"20040607" and thermal same (dissipate dissipation dissipated) same (top near (side surface)) same (bottom near (side surface)) same (component IC circuit) and (circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/14 17:07
S24	6	"257"/\$.ccls. and @ad<"20040607" and thermal same (dissipate dissipation dissipated) same (top near (side surface)) same (bottom near (side surface)) same (component IC circuit) same (high higher) same (low lower) and (circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/14 17:02
S25	37 ⁻	"257"/\$.ccls. and @ad<"20040607" and (thermal heat cool) same (dissipate dissipation dissipated) same (top or top near (side surface)) same (bottom or bottom near (side surface)) same (component IC circuit) same (high higher greater) same (low lower less) and (circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/14 17:08
S26	2	("20020018338").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/14 17:05
S27	1	"257"/\$.ccls. and @ad<"20040607" and thermal same (dissipate dissipation dissipated) same (top near (side surface)) same (bottom near (side surface)) same (component IC circuit) and (circuit adj board) and S26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/14 17:07
S28	12	("20010046749" "3169200" "64170 60" "6720704" "6876123").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/06 21:45

		LAST Scarc	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,			
S29	6	("20010046749" "3169200" "64170 60" "6720704" "6876123").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:39
S30	13257601	@ad<"20021127" @rlad<"20021127"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:41
S31	148210	tunneling tunnel	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:42
S32 ·	21245	S31 same electron	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:42
S33	899089	insulation insulator metal near oxide aluminum near oxide	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:43
S34	564	S30 and collector and emitter and S33 and S32	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:47
S35	131091	thermotunneling thermo-tunneling thermo tunneling	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:48
S36	344	S34 and S35	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:48
S37	92173	S30 and collector same emitter	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:48
S38	357	S30 and collector same emitter same S32 same S32	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:50

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S39	259	S38 and S35	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:49
S40	210	S39 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:49
S41	233	S30 and collector same emitter same S32 same S35	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:50
S42	233	S30 and collector same emitter same S32 same S35 same S32	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:51
S43	192	S30 and collector same emitter same (tunneling tunnel) same electron same (thermotunneling thermo-tunneling thermo tunneling) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:53
S44	14	S30 and collector same emitter same (tunneling tunnel) same electron same (thermotunneling thermo-tunneling thermo tunneling) same S33 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:57
S45	0	S30 and collector same emitter same (tunneling tunnel) same electron same S33 and (thermotunneling thermo-tunneling)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 22:57
S46	1	S30 and collector same emitter same S33 and (thermotunneling thermo-tunneling)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/06 23:00
S47	41	S30 and collector same emitter same (insulation insulator) and tunneling near electron	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 17:27
S48	580	257/30.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 17:34

S49	13257622	@ad<"20021127" @rlad<"20021127"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 17:34
S50	446	S48 and S49	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 17:34
S51	27	S50 and emitter and collector	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR .	ON .	2006/10/09 17:41
S52	1426300	cooling heat near (dissipating dissipation dissipate) cool	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 17:42
S53	36626	tunneling electron near tunneling	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 17:43
S54	1525460	insulator insulation dielectric insulating aluminum near oxide	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 17:43
S55	1972	S49 and S52 and S53 and S54	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 17:58
S56	28	S49 and S52 same S53 same S54	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 17:44
S57	699	S49 and S52 and S53 same S54	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 17:58
S58	671	S49 and S52 and S53 same S54 not S56	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 17:59

S59	616	S49 and S52 and S53 same S54 not S56 and temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 18:00
S60	188	S49 and S52 and (electron near tunneling) same S54 not S56 and temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 19:32
S61	283	S49 and S52 and (electron near10 tunneling) same S54 not S56 and temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 18:00
S62	14	S49 and S52 and (electron near tunneling) same S54 not S56 and (thermotunneling thermo adj2 tunneling thermionic therm adj ionic)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 19:33
S63		("20020033188" "20030042819" "20030184188" "20040029341" "20040189141" "20040207037" "3169200" "3173032" "3267308" "3579031" "3808477" "3843896" "3890161" "3899696" "3983423" "4040903" "4047093" "4151438" "4188571" "4266179" "4280074" "4281280" "4298768" "4303845" "4323808" "4346330" "4368416" "4373142" "4528417" "4667126" "4700099" "4750023" "4755350" "4771201" "4927599" "5028835" "5327038" "5459367" "5492570" "5541464" "5572042" "5578886" "5600200" "5623119" "5780954" "5841219" "5955772" "5973259" "5981071" "5994638" "6020671" "6022637" "6037697" "6060331" "6203939" "6323414" "6396191" "6403874" "6489704" "6534784" "6720704" "6779347").PN. OR ("6946596"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/09 20:24
S64	0	"5291274".pn. and cooling	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/09 20:24

S65	0	"5291274".pn. and cool	US-PGPUB;	OR	ON	2006/10/09 20:24
		JZJIZ/T ipiii alia cooi	USPAT; USOCR			2000, 10, 03 20.24
S66	1	"5291274".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/09 20:38
S67		("6396191"),PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/09 20:43
S68	377	coutts.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/10/09 20:43
S69	0	("t." near coutts).in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/09 20:43
S70	6	("t" near coutts).in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/09 20:51
S71	12	("20010046749" "3169200" "64170 60" "6720704" "6876123").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/09 20:51
S72	6	("20010046749" "3169200" "64170 60" "6720704" "6876123").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 20:53
S73	2181	(thermotunneling thermionic) and dielectric	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON .	2006/10/09 20:54

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S74	175	(thermotunneling thermionic) and dielectric same cooling	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 20:54
S75	93	(thermotunneling thermionic) and dielectric same cooling and S49	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/10/09 21:04
S76	2	("20030168957").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/10 13:27